Diodes Inc. Material Data Sheet
Rev: May 2009

SBR3U100LP-p SBR3U150LP-p SBR4U130LP-p

Part Number: **SBR DFN3030-8 Package** p = package designator
Weight (mg): 19.3399 See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	3.77	0.729	1000000	37694
Leadframe	C7025	Cu	7440-50-8	95.90%	52.02	10.0614	959000	498911
		Si	7440-21-3	0.73%			7250	3772
		Ni	7440-02-0	3.20%			32000	16648
		Mg	7439-95-4	0.18%			1750	910
Leadframe Plating	Intenal plating	Ni	7440-02-0	100.00%	1.20	0.2326	1000000	12027
	middle plating	Pd	2023568	100.00%	0.11	0.0212	1000000	1096
	outer plating	Au	7440-57-5	100.00%	0.02	0.0042	1000000	217
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	1.34	0.2583	1000000	13356
Encapsulation	EME-G770HCD	Silica fused	60676-86-0	93.50%	39.73	7.6847	935000	371522
		Epoxy resin	------	3.00%			30000	11920
		Phenol resin	------	3.00%			30000	11920
		Carbon Black	1333-86-4	0.50%			5000	1987
Die Attach Epoxy	QMI519	Ag	7440-22-4	80.00%	1.80	0.3485	800000	14416
		palladium compound	----	0.15%			1500	27
		2,6-Di-tert-butyl-p-cresol	128-37-0	0.01%			50	1
		Hydroquinone	123-31-9	0.00%			1	0
		Acrylate	----	15.84%			158449	2855
		Bismaleimide resin	----	3.00%			30000	541
		Polymer of polybutadiene and anlydride	----	1.00%			10000	180
				Total	100.00	19.3399		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

***** The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, *Material Composition Declaration for Electronic Products*.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos
Antimony Compounds
Azo compounds
Cadmium and cadmium compounds
Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Dimethyl fumarate
Halogens
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Red Phosphorous
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

REACH SVHCs and other Substances of Concern:
Anthracene
4,4'- Diaminodiphenylmethane
Dibutyl phthalate
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate

Beryllium, Beryllium Alloys and Compounds
Hydrazine
Tetrachloroethylene
Toluene
Toluene Diisocyanate
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Bis(tributyltin)oxide
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate

Methylene Chloride
Trichloroethene
Methyl Ethyl Ketone
Xylenes